

Customer Inquiry Etcher Requirements Survey

Please provide as much information as possible in the following survey and email it to sales@allwin21.com / allwin21corp@gmail.com. The more complete and accurate your responses, the better we can recommend the most suitable Plasma Etcher model or configuration for your specific needs, based on our 45 years of Plasma Etcher experience and hundreds of successful installations worldwide. Completing the survey thoroughly will ensure optimal system performance while avoiding unnecessary options that do not contribute to your application. We greatly appreciate your time and effort.

Section 1: Contact Information

- (1) Full Name:
- (2) Email Address:
- (3) Company Name:
- (4) Company Address:
- (5) Phone Number (Option):

Section 2: Plasma Etcher System Requirements

- (1) Type of Plasma Etcher System Required:
 Semi-Automatic Batch; Fully Automatic Single Wafer; Others:
- (2) Substrate Size (Small Pieces, 1", 2", 3", 4", 5", 6", 8", Others) :
- (3) Substrate Material (Si, GaAs, GaN, SiC, InP, GaInP, AlN, Quartz, Others) :
- (4) Etching Material (**Polysilicon, Silicon Nitride, Silicon Dioxide**, Al, TiW, W, Others) :
- (5) List All of Process Gases:
- (6) Maximum, Typical, Minimum Temperature Requirements (°C):
- (7) Maximum, Typical, Minimum Duration Requirements (Seconds):
- (8) Plasma Power Requirements:
 300W, 13.56MHz RF; 600W, 13.56MHz RF; 1000W, 13.56MHz RF; Others:
- (9) Base vacuum pressure specification if applicable:
- (10) Etcher rate and uniformity specifications if applicable:
- (11) Network / automation functions such as EAP, GEM/SECS: Yes; No; Others:
- (12) Need Low RF Damage Plasma Etcher system: Yes; No

Section 3: Previous Experience & Brand Awareness

- (1) Have you previously used any Plasma Etcher system that met your requirements? If yes, please specify brand and model:
- (2) Are you familiar with **Matrix, Tegal, Branson/IPC, Gasonics, Lam Research** plasma Etcher systems? If yes, please specify the model(s):

Section 5: Project & Procurement Information

- (1) Approximate Budget:
- (2) Estimated Purchase Timeline:
- (3) Throughput Requirements (e.g., wafers/hour/Day/Week/Month/Year):
- (4) Application Background and Other Special Requirements: